

# GOOLED

# GooLED-LG-8630 Pin Fin Heat Sink Φ86.5mm for LG Innotek

## **Features VS Benefits**

- \* The GooLED-LG-8630 LG Innotek Pin Fin LED Heat Sinks are specifically designed for luminaires using the LG Innotek LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 1,200 to 3,200 lumen.
- \* Thermal resistance range Rth 2.5°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of LG Innotek COB series.
- \* Diameter 86.5mm standard height 30.0mm Other heights on request.
- \* Forged from highly conductive aluminum.

### Zhaga LED engine and radiator assembly is a unified future international standardization

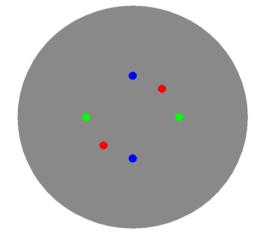
- \* Below you find an overview of LG Innotek COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.











# **LG Innotek LED Modules directly Mounting Options**

LG Innotek 42W&56W COB series.

LEMWM28D80xxxxx; LEMWM28D90xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.

#### LG Innotek 21W&32W COB series.

With the Zhaga Book 3 holders for the green indicator marks.

TE Connectivity Holder: 2213130-1;

Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
Olivia series: FN14637-S; FN14828-M;





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# **Mounting Options and Drawings & Dimensions**

Example:GooLED-LG-8630-B-1,2

Example:GooLED-LG-86 1 - 2 - 3

1 Height (mm)

**Anodising Color** 

B-Black

C-Clear

**Z-Custom** 

Mounting Options - see graphics for details Combinations available

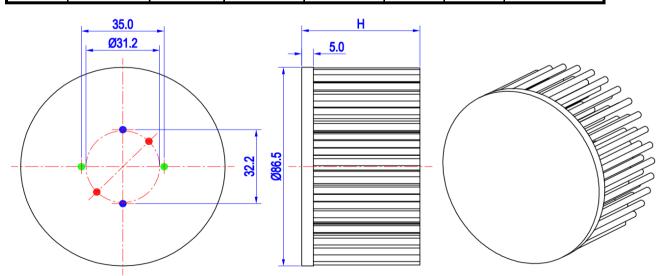
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means option 1 and 2 combined

## Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Stella Series	Olivia series	INCEAD	DEPTH	DISTANCE
1	21W&32W COB	/	/	FN14637-S; FN14828-M;	МЗ	6.5mm	31.2mm/ 2-@180°
2	42W&56W COB	/			МЗ	6.5mm	32.2mm/ 2-@180°
3	21W&32W COB	BJB Holder 47.319.2011.50			МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
		TE Holder 2213130-1					
	42W&56W COB	BJB Holder 47.319.2030.50					
		TE Holder 2213480-1					







# The product deta table

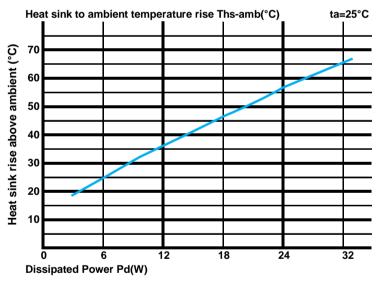


Model No.	GooLED-LG-8630		
Heatsink Size	Ф86.5хH30mm		
Heatsink Material	AL1070		
Finish	Black Anodized		
Weight (g)	152.0		
Dissipated power (Ths-amb,50℃)	20.0 (W)		
Cooling surface area (mm²)	48926		
Thermal Resistance (Rhs-amb)	2.5 (°C/W)		

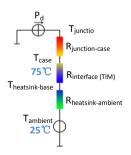
## The thermal data table

- \* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- \*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (1-\eta L)$ .
  - Pd Dissipated power ; Pe Electrical power ;  $\eta L = \text{Light effciency of the LED module};$

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)		
		GooLED-LG-8630			
Dissipated Power Pd(W)	6.0	4.00	24.0		
	12.0	2.92	35.0		
	18.0	2.56	46.0		
	24.0	2.33	56.0		
	32.0	2.03	65.0		



- \*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:mingFa} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$
- $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.\ I-0.\ I\ 5mm\ is\ recommended.$



- \*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths Ta)/Pd$
- $\theta$  Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- \*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{junction-case}$ , the thermal resistance of the TIM outside the package is  $R_{interface (TIM)}[^{\circ}C/M]$ , the thermal resistance with the heat sink is  $R_{heatsink-ambient}[^{\circ}C/M]$ , and the ambient temperature is  $T_{ambient}[^{\circ}C]$ .
- \*Thermal resistances outside the package  $R_{interface \, (TIM)}$  and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:  $T_{junction} = (R_{junction-case} + R_{case-ambient})^{p}Pd + T_{ambient}$

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